Remarks

The Examiner is requested to clarify the Statement of reasons for allowance.

In the Notice of Allowability at pages 3-4, the Examiner made a statement of reasons for allowance, stating as follows with regard to Ellis-Monaghan (USP 6,495,917) (emphasis added):

> ...Also, Ellis Monaghan (U.S. Pat. No. 6,495,917) teaches a bond pad structure in a semiconductor die *comprising a first bond pad and a second bond pad* comprising a plurality of lower metal layers and an upper metal layer...

In the Office Action, mailed August 11, 2005, the Examiner stated as follows (page 7; emphasis added):

> However, Preslar et al. does not disclose the pad having a plurality of lower metal layers. Ellis-Monaghan et al. in e.g., Fig. 36 and column 7, line 51- column 8, line 23 *a pad (LM-1 — LM-3 and 361)* having a plurality of lower metal layers (LM-1 — LM-3) under an upper metal layer (361). Thus, it would have been obvious to one of ordinary skill in the art at the time when the invention was made to modify Preslar et al. by adding another lower metal layer on the lower metal layer of Preslar et al. as taught by Ellis-Monaghan...

In the Response filed October 11, 2005, at page 20, Applicant stated as follows:

> The Examiner cites Ellis Monaghan as disclosing a pad (361) having a plurality of lower metal layers (LM1 LM3) under an upper metal layer (361), citing to FIG. 36, and col. 7, line 51 to col. 8, line 23. The Examiner asserts that it would be obvious to modify Preslar by adding another lower metal layer on the lower metal layer of Preslar based on Ellis Monaghan.
>
> Ellis Monaghan's disclosure fails to cure the base deficiency of the Preslar in teaching Applicant's devices as claimed. As stated above, Preslar teaches a bond pad structure in which both bond pads are operable as both a test enable bond pad and an operational bond pad.
>
> The combination of the disclosure of Ellis Monaghan with Preslar does not make obvious Applicant's bond pad structure as claimed. Accordingly, withdrawal of this rejection of the claims is respectfully requested.

The Examiner's statement that Ellis-Monaghan teaches a bond pad structure in FIG. 36 comprising *a first bond pad and a second bond pad* is incorrect and inconsistent with the statements made in the Office Action of August 11, 2005.

In FIG. 36, Ellis-Monaghan teaches the placement of a solder ball C4 (360) on a *single* metal layer – *LM layer 361*. See FIG. 36 below, and at col. 8 (emphasis added):

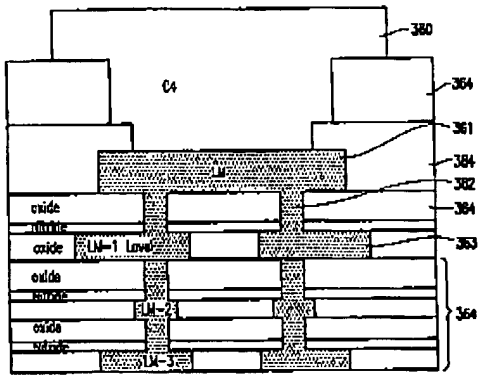

FIG. 36

> Referring now to FIGS. 35 and 36, another embodiment of the invention is illustrated ...The C4 structure is shown as item 360, *the last metallization layer is shown as item 361*, the next to last metallization layer is shown as item 363, and the bar via connecting the last metallization layer 361 to the second to last metallization layer 363 is shown as item 362 in FIGS. 35 and 36. In addition, FIG. 36 illustrates various dielectric insulating layers 364...

Contrary to the Examiner's statement, Ellis-Monaghan does *not* teach or suggest first and second bond pads. Pad "LM" (element 361) is a *single* contact surface for solderball C4 wiring layer 360.

The Examiner is requested to issue a clarification of the Statement of reasons for allowance with regard to the citation of Ellis-Monaghan.

Extension of Term. The proceedings herein are for a patent application and the provisions of 37 CFR § 1.136 apply. Applicant believes that no extension of term is required. However, this conditional petition is being made to provide for the possibility that Applicant has inadvertently overlooked the need for a petition for extension of time. If any extension and/or fee are required, please charge Account No. 23-2053.

The Examiner is urged to telephone the undersigned attorney if any questions should arise.

Respectfully submitted,

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